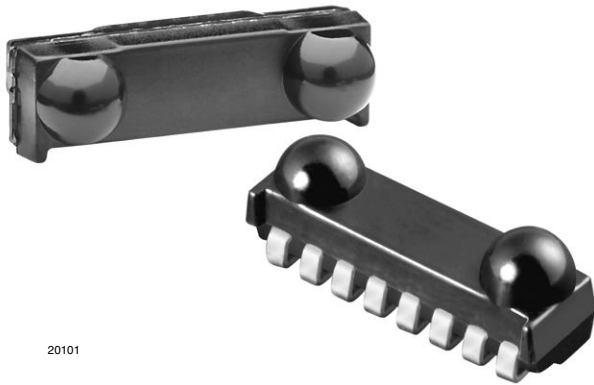




Infrared Transceiver Module (SIR, 115.2 kbit/s) for IrDA® Applications



20101

DESCRIPTION

TFDU4301 is an infrared transceiver that supports data rates up to 115 kbit/s per the IrDA standard. The link distance is up to 1 meter. The transceiver includes a PIN photodiode, an infrared emitter, and a low-power control IC. These components have not been qualified according to automotive specifications.

FEATURES

- Compliant to the IrDA physical layer specification
- Standard IrDA link distance of 1 m
- Low power consumption, typically less than 70 μ A
- Less than 1 μ A in shutdown mode
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

APPLICATIONS

- Short-distance wireless communication and data transfer
- Use in environments where RF is problematic

LINKS TO ADDITIONAL RESOURCES



Product Page

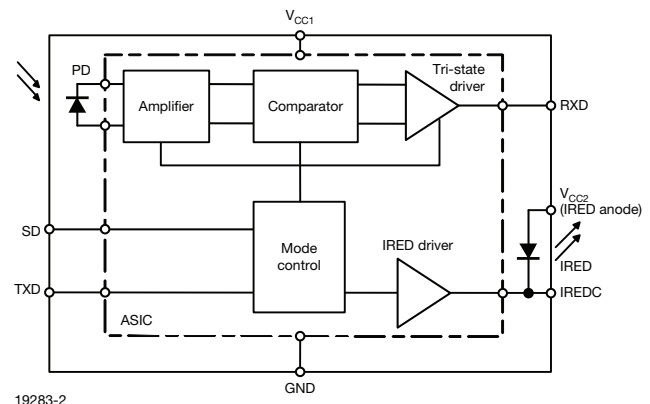


Related Documents

DESIGN SUPPORT TOOLS

- [3D model](#)
- [Window size calculator](#)
- [Symbols and terminology](#)
- [IRDC protocol](#)
- [Reference layouts and circuit diagrams](#)

FUNCTIONAL BLOCK DIAGRAM



**PRODUCT SUMMARY**

PART NUMBER	DATA RATE (kbit/s)	DIMENSIONS H x L x W (mm x mm x mm)	LINK DISTANCE (m)	OPERATING VOLTAGE (V)	IDLE SUPPLY CURRENT (mA)
TFDU4301	115.2	3.1 x 8.5 x 2.5	0 to ≥ 1	2.4 to 5.5	0.07

PARTS TABLE

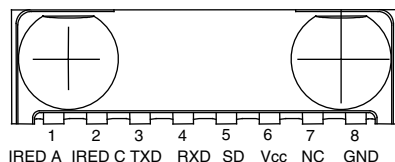
PART	DESCRIPTION	QTY/REEL
TFDU4301-TR1	Oriented in carrier tape for side view surface mounting	750 pcs
TFDU4301-TR3	Oriented in carrier tape for side view surface mounting	2500 pcs
TFDU4301-TT1	Oriented in carrier tape for top view surface mounting	750 pcs
TFDU4301-TT3	Oriented in carrier tape for top view surface mounting	2500 pcs

PIN DESCRIPTION

PIN NUMBER	FUNCTION	DESCRIPTION	I/O	ACTIVE
1	V _{CC2} IRED anode	Connect IRED anode directly to the power supply (V _{CC2}). IRED current can be decreased by adding a resistor in series between the power supply and IRED anode. A separate unregulated power supply can be used at this pin		
2	IRED cathode	IRED cathode, internally connected to the driver transistor		
3	TXD	This Schmitt-Trigger input is used to transmit serial data when SD is low. An on-chip protection circuit disables the LED driver if the TXD pin is asserted for longer than 100 μs. The input threshold voltage adapts to and follows the logic voltage swing defined by the applied supply voltage	I	High
4	RXD	Received data output, push-pull CMOS driver output capable of driving standard CMOS or TTL loads. During transmission the RXD output is active and mirrors the transmit signal. No external pull-up or pull-down resistor is required. Floating with a weak pull-up of 500 kΩ (typ.) in shutdown mode. The voltage swing is defined by the applied supply voltage	O	Low
5	SD	Shutdown. The input threshold voltage adapts to and follows the logic voltage swing defined by the applied supply voltage	I	High
6	V _{CC1}	Supply voltage		
7	NC	Not connected	I	
8	GND	Ground		

PINOUT

TFDU4301
weight 77 mg



18101-1

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage range, transceiver	$-0.3\text{ V} < V_{CC2} < 6\text{ V}$	V_{CC1}	-0.5	-	+6	V
Supply voltage range, transmitter	$-0.5\text{ V} < V_{CC1} < 6\text{ V}$	V_{CC2}	-0.5	-	+6	V
RXD output voltage	$-0.5\text{ V} < V_{CC1} < 6\text{ V}$	V_{RXD}	-0.5	-	$V_{CC1} + 0.5$	V
Voltage at all inputs	Note: $V_{in} \geq V_{CC1}$ is allowed	V_{IN}	-0.5	-	+6	V
Input current	For all pins, except IRED anode pin		-	-	10	mA
Output sinking current			-	-	25	mA
Power dissipation		P_D	-	-	250	mW
Junction temperature		T_J	-	-	125	°C
Ambient temperature range (operating)		T_{amb}	-25	-	+85	°C
Storage temperature range		T_{stg}	-25	-	+85	°C
Soldering temperature	See recommended solder profile		-	-	260	°C
Average output current, pin 1		$I_{IRED(DC)}$	-	-	85	mA
Repetitive pulsed output current, pin 1 to pin 2	$t < 90\text{ }\mu\text{s}$, $t_{on} < 20\text{ }\%$	$I_{IRED(RP)}$	-	-	430	mA
ESD protection	JESD22-A114	V_{ESD}	2	-	-	kV
Latchup	JESD78		$ \pm 100 $	-	-	mA
Thermal resistance junction to ambient	JESD51	R_{thJA}	-	300	-	K/W

Note

- Reference point ground (pin 8) unless otherwise noted.
Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing

EYE SAFETY INFORMATION

STANDARD	CLASSIFICATION
IEC/EN 60825-1 (2007-03), DIN EN 60825-1 (2008-05) "SAFETY OF LASER PRODUCTS - Part 1: equipment classification and requirements", simplified method	Class 1
IEC 62471 (2006), CIE S009 (2002) "Photobiological Safety of Lamps and Lamp Systems"	Exempt
DIRECTIVE 2006/25/EC OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL of 5 th April 2006 on the minimum health and safety requirements regarding the exposure of workers to risks arising from physical agents (artificial optical radiation) (19 th individual directive within the meaning of article 16(1) of directive 89/391/EEC)	Exempt

Note

- Vishay transceivers operating inside the absolute maximum ratings are classified as eye safe according the above table



ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{CC1} = V_{CC2} = 2.4\text{ V}$ to 5.5 V unless otherwise noted)						
PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
TRANSCEIVER						
Supply voltage		V_{CC1}	2.4	-	5.5	V
Operating temperature range		T_{amb}	-25	-	+85	$^{\circ}\text{C}$
Data rates			9.6	-	115.2	kbit/s
Idle supply current at V_{CC1} (receive mode, no signal)	SD = low, $T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ independent of ambient light, $V_{CC1} = V_{CC2} = 2.4\text{ V}$ to 5.5 V	I_{CC1}	40	70	110	μA
Average dynamic supply current, transmitting	$I_{IRED} = 300\text{ mA}$, 20 % duty cycle	I_{CC1}	-	0.6	2	mA
Standby (SD) ⁽¹⁾ supply current	SD = high, $T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ independent of ambient light	I_{SD}	-	0.01	1	μA
RXD to V_{CC1} impedance	SD = high	R_{RXD}	400	500	600	$\text{k}\Omega$
Input voltage low (TXD, SD)		V_{ILO}	-0.3	-	0.4	V
Input voltage high (SD)	For compliance with ISD spec.	V_{IHI}	$V_{CC1} - 0.3$	-	6	V
Input voltage high (TXD)		V_{IHI}	$V_{CC1} - 0.5$	-	6	V
Timing logic decision level			-	$0.5 \times V_{CC1}$	-	
Input leakage current low	$V_{ILO} \leq 0.3\text{ V}$	I_{ILO}	-	0.01	10	μA
Input leakage current high	$V_{IHI} \geq V_{CC1} - 0.3\text{ V}$	I_{IHI}	-	0.01	10	μA
Input capacitance (TXD, SD)		C_{IN}	-	-	5	pF
Output voltage low, RXD	$C_{load} = 8\text{ pF}$, $I_{OLO} \leq +500\text{ }\mu\text{A} $	V_{OLO}	-	-	$0.15 \times V_{CC1}$	V
Output voltage high, RXD	$I_{OH} = 200\text{ }\mu\text{A}$	V_{OHI}	$0.8 \times V_{CC1}$	-	-	V

Notes

- Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing
- ⁽¹⁾ SD mode becomes active when SD is set high for more than 0.2 μs . In SD mode the detector is disabled and the output disconnected



OPTOELECTRONIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{CC1} = V_{CC2} = 2.4\text{ V to }5.5\text{ V}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
RECEIVER						
Minimum irradiance E_e in angular range ⁽²⁾	9.6 kbit/s to 115.2 kbit/s, $\lambda = 850\text{ nm to }900\text{ nm}$; $\alpha = 0^{\circ}, 15^{\circ}$	E_e	-	20	50	mW/m ²
Maximum irradiance E_e In Angular Range ⁽³⁾	$\lambda = 850\text{ nm to }900\text{ nm}$	E_e	2	5	-	kW/m ²
Maximum no detection irradiance ⁽¹⁾	$\lambda = 850\text{ nm to }900\text{ nm}$, $t_r, t_f < 40\text{ ns}$, $t_{po} = 1.6\text{ }\mu\text{s}$ at $f = 115\text{ kHz}$, no output signal allowed	E_e	4 (0.4)	-	-	mW/m ² ($\mu\text{W/cm}^2$)
Rise time of output signal	10 % to 90 %, $C_L = 8\text{ pF}$	$t_{r(RXD)}$	10	30	80	ns
Fall time of output signal	90 % to 10 %, $C_L = 8\text{ pF}$	$t_{f(RXD)}$	10	30	80	ns
RXD pulse width of output signal	Input pulse length $> 1.2\text{ }\mu\text{s}$	t_{PW}	1.7	2.2	3	μs
Stochastic jitter, leading edge	Input irradiance = 100 mW/m^2 , $\leq 115.2\text{ kbit/s}$		-	-	350	ns
Standby/shutdown delay, receiver startup time	After shutdown active or power-on		-	100	500	μs
Latency		t_L	-	50	150	μs
TRANSMITTER						
IRED operating current limitation	No external resistor for current limitation ⁽⁴⁾	I_D	200	300	430	mA
Forward voltage of built-in IRED	$I_f = 300\text{ mA}$	V_f	1.4	1.8	1.9	V
Output leakage IRED current	$TXD = 0\text{ V}$, $0 < V_{CC1} < 5.5\text{ V}$	I_{IRED}	-1	0.01	1	μA
Output radiant intensity	$\alpha = 0^{\circ}, 15^{\circ}$, $TXD = \text{high}$, $SD = \text{low}$	I_e	50	200	400	mW/sr
	$V_{CC1} = 5\text{ V}$, $\alpha = 0^{\circ}, 15^{\circ}$, $TXD = \text{low or } SD = \text{high}$ (receiver is inactive as long as $SD = \text{high}$)	I_e	-	-	0.04	mW/sr
Output radiant intensity, angle of half intensity		α	-	± 30	-	$^{\circ}$
Peak - emission wavelength ⁽⁵⁾		λ_p	870	-	910	nm
Spectral bandwidth		$\Delta\lambda$	-	45	-	nm
TRANSMITTER						
Optical rise time, fall time		t_{ropt}, t_{fopt}	10	50	100	ns
Optical output pulse duration	Input pulse width $1.6 < t_{TXD} < 23\text{ }\mu\text{s}$	t_{opt}	$t_{TXD} - 0.15$	-	$t_{TXD} + 0.15$	μs
	Input pulse width $t_{TXD} \geq 23\text{ }\mu\text{s}$	t_{opt}	23	50	100	μs
Optical overshoot			-	-	25	%

Notes

- Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing
- ⁽¹⁾ Equivalent to IrDA background light and electromagnetic field test: fluorescent lighting immunity
- ⁽²⁾ IrDA sensitivity definition: minimum irradiance E_e in angular range, power per unit area. The receiver must meet the BER specification while the source is operating at the minimum intensity in angular range into the minimum half-angular range at the maximum link length
- ⁽³⁾ Maximum irradiance E_e in angular range, power per unit area. The optical delivered to the detector by a source operating at the maximum intensity in angular range at minimum link length must not cause receiver overdrive distortion and possible related link errors. If placed at the active output interface reference plane of the transmitter, the receiver must meet its bit error ratio (BER). For more definitions see the document "Symbols and Terminology" on the Vishay website
- ⁽⁴⁾ Using an external current limiting resistor is allowed and recommended to reduce IRED intensity and operating current when current reduction is intended to operate at the IrDA low power conditions. E.g. for $V_{CC2} = 3.3\text{ V}$ a current limiting resistor of $R_S = 56\text{ }\Omega$ will allow a power minimized operation at IrDA low power conditions
- ⁽⁵⁾ Due to this wavelength restriction compared to the IrDA spec of 850 nm to 900 nm the transmitter is able to operate as source for the standard remote control applications with codes as e.g. Phillips RC5/RC6[®] or RECS 80



RECOMMENDED CIRCUIT DIAGRAM

Operated with a clean low impedance power supply the TFDU4301 needs no additional external components. However, depending on the entire system design and board layout, additional components may be required (see Fig. 1).

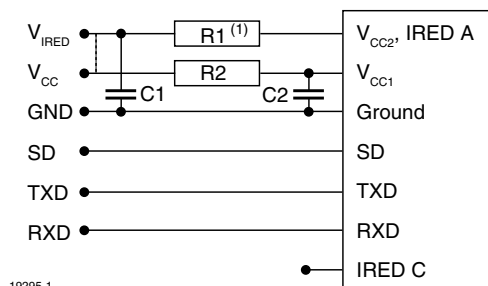


Fig. 1 - Recommended Application Circuit

Note

(1) R1 is optional when reduced intensity is used

The capacitor C1 is buffering the supply voltage and eliminates the inductance of the power supply line. This one should be a tantalum or other fast capacitor to guarantee the fast rise time of the IRED current. The resistor R1 is the current limiting resistor, which may be used to reduce the operating current to levels below the specified controlled values for saving battery power.

Vishay's transceivers integrate a sensitive receiver and a built-in power driver. The combination of both needs a careful circuit board layout. The use of thin, long, resistive and inductive wiring should be avoided. The shutdown input must be grounded for normal operation, also when the shutdown function is not used.

TABLE 1 - RECOMMENDED APPLICATION CIRCUIT COMPONENTS

COMPONENT	RECOMMENDED VALUE
C1	4.7 μ F
C2	0.1 μ F, ceramic
R1	Depends on current to be adjusted
R2	47 Ω

The inputs (TXD, SD) and the output RXD should be directly connected (DC - coupled) to the I/O circuit. The capacitor C2 combined with the resistor R2 is the low pass filter for smoothing the supply voltage. R2, C1 and C2 are optional and dependent on the quality of the supply voltages V_{CC1} and injected noise. An unstable power supply with dropping voltage during transmission may reduce the sensitivity (and transmission range) of the transceiver.

The placement of these parts is critical. It is strongly recommended to position C2 as close as possible to the transceiver pins.

When extended wiring is used as in bench tests the inductance of the power supply can cause dynamically a voltage drop at V_{CC2} . Often some power supplies are not able to follow the fast current rise time. In that case another 4.7 μ F (type, see table under C1) at V_{CC2} will be helpful.

Under extreme EMI conditions as placing an RF-transmitter antenna on top of the transceiver, we recommend to protect all inputs by a low-pass filter, as a minimum a 12 pF capacitor, especially at the RXD port.

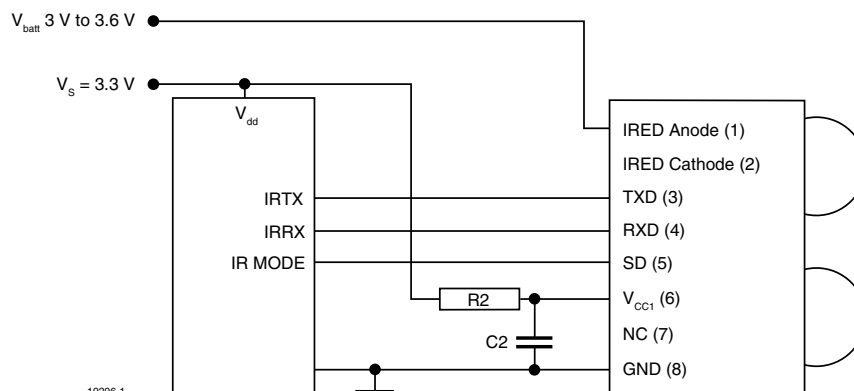


Fig. 2 - Typical Application Circuit

Figure 2 shows an example of a typical application for to work with a separate supply voltage V_S and using the transceiver with the IRED Anode connected to the unregulated battery V_{batt} . This method reduces the peak load of the regulated power supply and saves therefore

costs. Alternatively all supplies can also be tied to only one voltage source. R1 and C1 are not used in this case and are depending on the circuit design in most cases not necessary.



I/O AND SOFTWARE

In the description, already different I/Os are mentioned. Different combinations are tested and the function verified with the special drivers available from the I/O suppliers. In special cases refer to the I/O manual, the Vishay application notes, or contact directly Vishay Sales, Marketing or Application.

For operating at RS232 ports we recommend to use an encoder / decoder-module.

Note

- TFDU4301 echoes the TXD signal at the RXD output during transmission. For communication this signal is to be correctly ignored by the controller or the software. The echo signal is implemented for test purposes in mass production

TABLE 2 - TRUTH TABLE

INPUTS			OUTPUTS		REMARK
SD	TXD	OPTICAL INPUT IRRADIANCE mW/m ²	RXD	TRANSMITTER	OPERATION
High > 1 ms	x	x	Weakly pulled (500 kΩ) to V _{CC1}	0	Shutdown
Low	High	x	Low (active)	I _e	Transmitting
Low	High > 100 μs	x	High inactive	0	Protection is active
Low	Low	< 4	High inactive	0	Ignoring low signals below the IrDA defined threshold for noise immunity
Low	Low	> min. detection threshold irradiance < max. detection threshold irradiance	Low (active)	0	Response to an IrDA compliant optical input signal
Low	Low	> max. detection threshold irradiance	Undefined	0	Overload conditions can cause unexpected outputs

ASSEMBLY INSTRUCTIONS

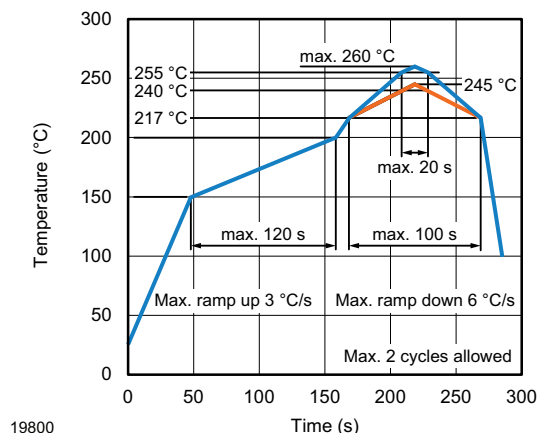
Reflow Soldering

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

Manual Soldering

- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off

VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE



Technical drawing of a progressive die, showing cross-sections A-A and B-B, and a top view of the die body.

Section A-A (Left): Shows a cross-section of the die body with a width of 2.55 and a chamfer angle of 8° max.

Section B-B (Top Right): Shows a cross-section of the die body with a width of 8.7, a height of 0.33, and a chamfer angle of 4° max. The section is labeled B-B.

Top View (Center): Shows the die body with a width of 16 and a height of 7.5. It features a series of circular holes with a diameter of $\phi 1.5$. The holes are spaced at intervals of 1.75. The top view is labeled with dimensions 16, 7.5, 1.75, and $\phi 1.5$.

Section A-A (Bottom Left): Shows a cross-section of the die body with a width of 2.55 and a chamfer angle of 8° max.

Section B-B (Bottom Right): Shows a cross-section of the die body with a width of 8.7, a height of 0.33, and a chamfer angle of 4° max. The section is labeled B-B.

Progressive direction: Indicated by an arrow pointing upwards.

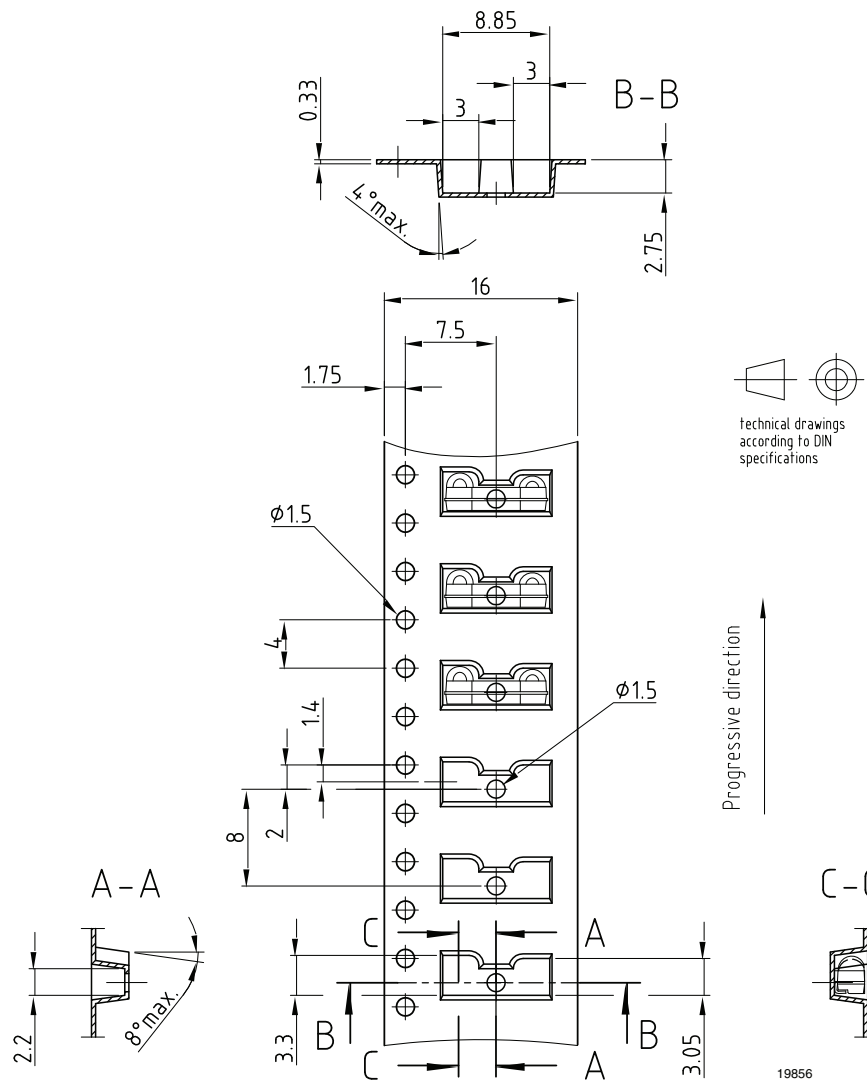
Technical drawings according to DIN specifications: Indicated by a symbol.

19855

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TAPE DIMENSIONS FOR TR1 AND TR3 in millimeters

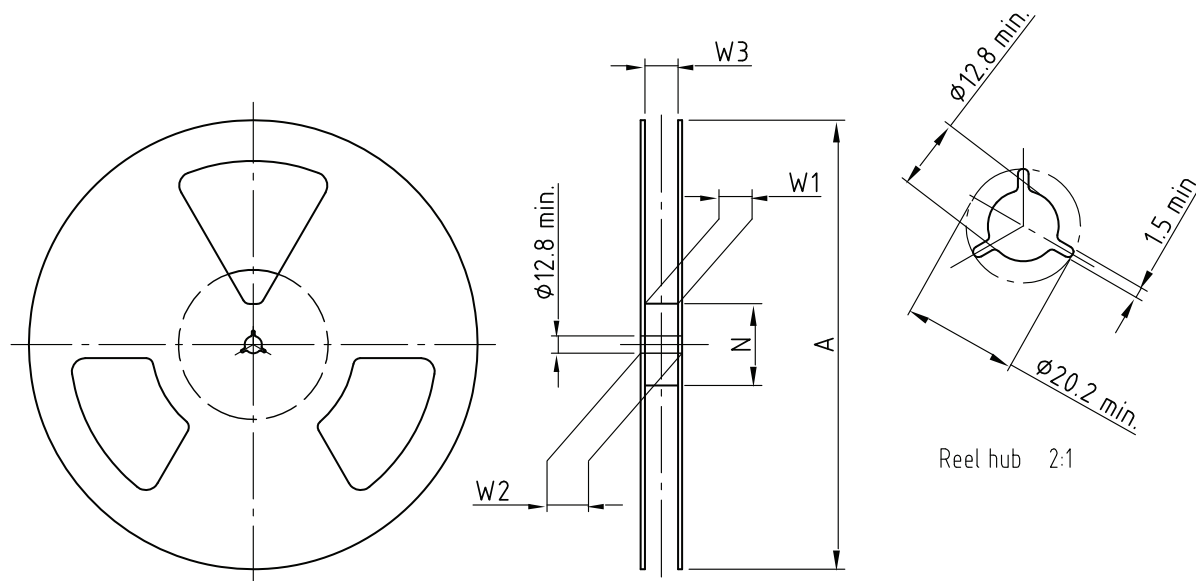


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Issue: 1; 08.12.04
19856

Fig. 4 - Tape Drawing, TFDU4301 for Side View Mounting



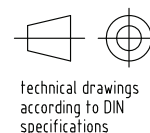
REEL DIMENSIONS in millimeters



Drawing-No.: 9.800-5090.01-4
Issue: 1; 29.11.05
14017

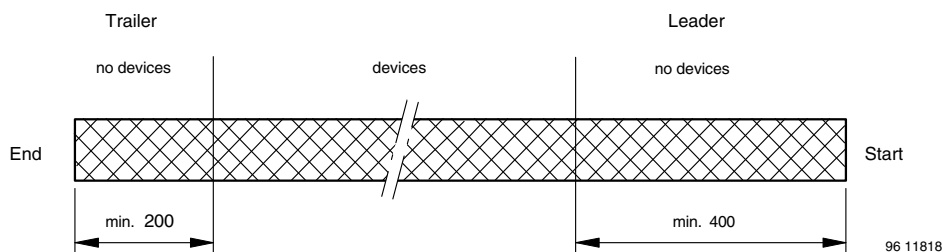
Form of the leave open
of the wheel is supplier specific.

Dimension acc. to IEC EN 60 286-3



TAPING VARIANT	TAPE WIDTH (mm)	A MAX. (mm)	N (mm)	W ₁ MIN. (mm)	W ₂ MAX. (mm)	W ₃ MIN. (mm)	W ₃ MAX. (mm)
TT1 / TR1	16	180	60	16.4	22.4	15.9	19.4
TT3 / TR3	16	330	50	16.4	22.4	15.9	19.4

LEADER AND TRAILER DIMENSIONS in millimeters



COVER TAPE PEEL STRENGTH

According to DIN EN 60286-3

0.1 N to 1.3 N

300 ± 10 mm/min.

165° to 180° peel angle

LABEL

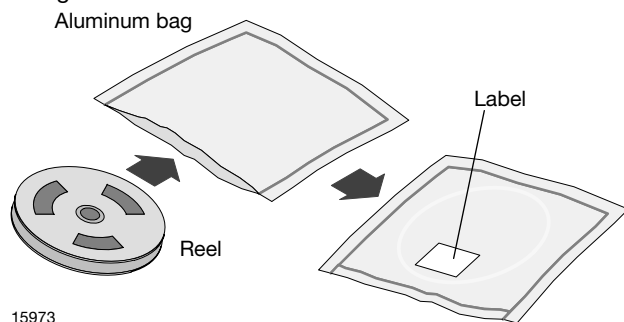
Standard bar code labels for finished goods

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.



DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



15973

FINAL PACKING

The sealed reel is packed into a cardboard box.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

After more than 72 h under these conditions moisture content will be too high for reflow soldering.

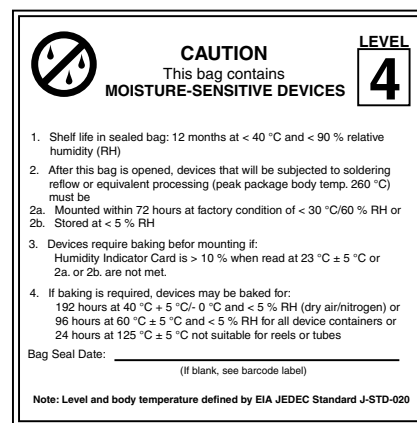
In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at 40 °C + 5 °C / - 0 °C and < 5 % RH (dry air / nitrogen) or

96 h at 60 °C + 5 °C and < 5 % RH for all device containers or

24 h at 125 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC® standard J-STD-020 level 4 label is included on all dry bags.



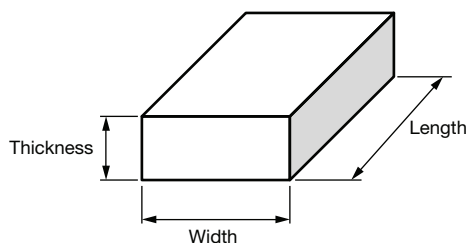
22522

EIA JEDEC standard J-STD-020 level 4 label is included on all dry bags

OUTER PACKAGING

The sealed reel is packed into a pizza box.

CARTON BOX DIMENSIONS in millimeters



22127

ORDER CODE	BOXING	THICKNESS	WIDTH	LENGTH
TT3 / TR3	Pizza box (taping in reels)	50	340	340
TT1 / TR1	Pizza box (taping in reels)	32	190	190



VISHAY SEMICONDUCTOR GmbH STANDARD BAR CODE PRODUCT LABEL (finished goods)		
PLAIN WRITING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
Long bar code top	Type	Length
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
Short bar code bottom	Type	Length
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.

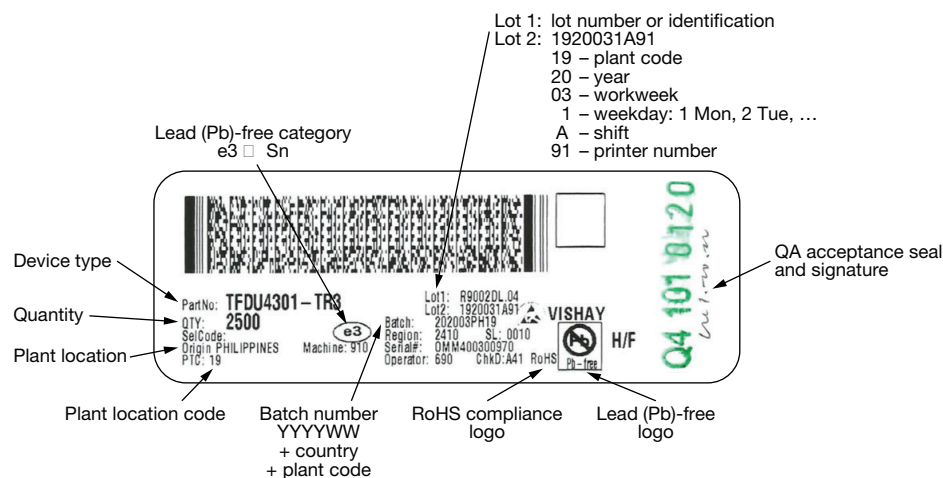


Fig. 5 - 2D Bar Code Label (according the bar code standard for 2D label PDF 417)
for a Lead (Pb)-Free Device Made in Philippines, Detailed Description

ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electrostatic sensitive devices warning labels are on the packaging.



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